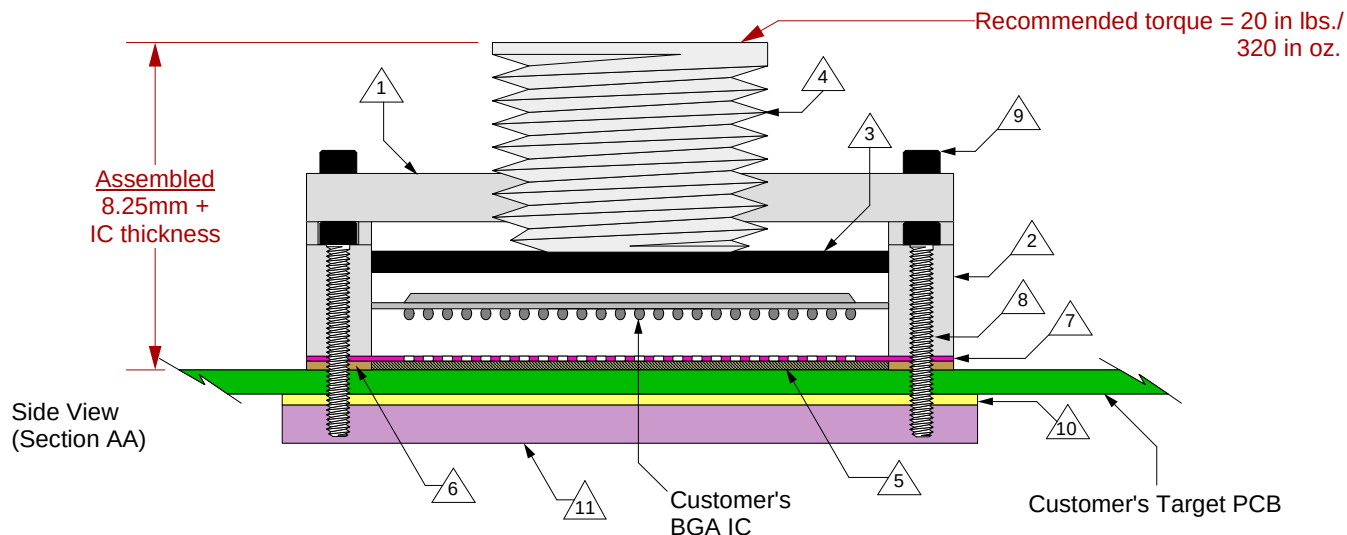
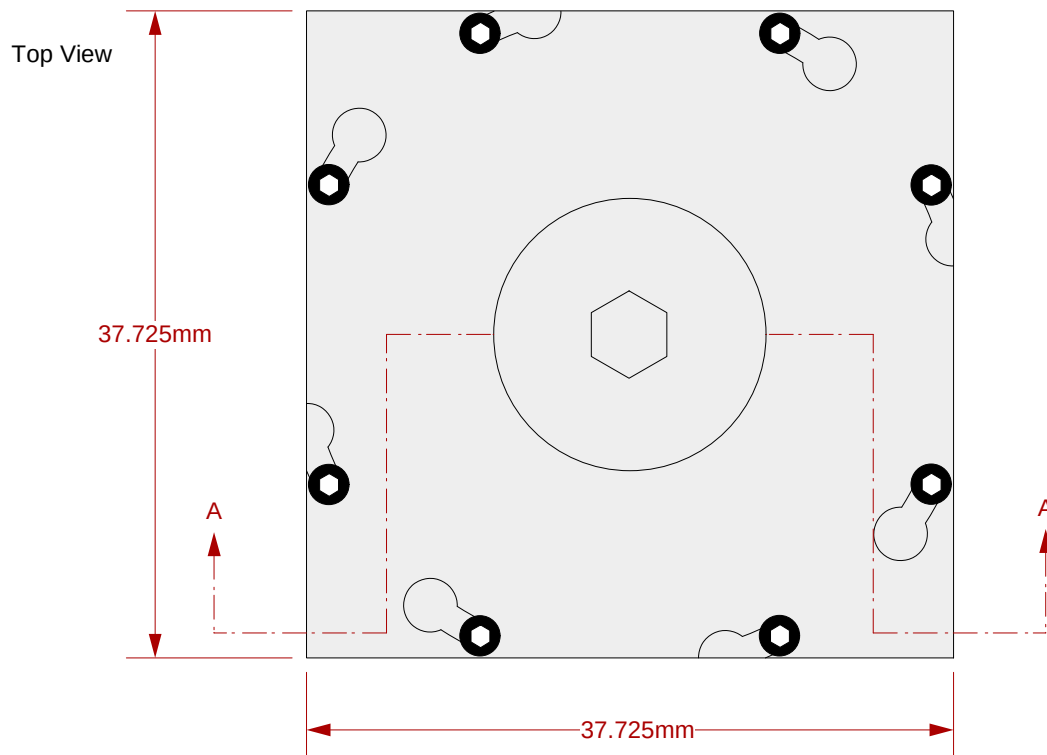




GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

- | | |
|----|--|
| 1 | Socket Lid: Black anodized Aluminum.
Thickness = 2.5mm. |
| 2 | Socket base: Black anodized Aluminum.
Thickness = 9.5mm. |
| 3 | Compression Plate: Black anodized Aluminum.
Thickness = 2.5mm. |
| 4 | Compression screw: Clear anodized Aluminum.
Thickness = 5mm, Hex socket = 5mm. |
| 5 | Elastomer: 40 micron dia gold plated brass
filaments arranged symmetrically in a silicone
rubber (63.5 degree angle).
Thickness = 0.75mm. |
| 6 | Elastomer Guide: Cirlex or equivalent.
Thickness = 0.725mm. |
| 7 | Ball Guide: Kapton polyimide. |
| 8 | Socket base screw: Socket head cap, alloy steel with
black oxide finish, 0-80 fine thread, 12.7mm long. |
| 9 | Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine
thread. |
| 10 | Insulation Plate: FR4/G10, Thickness = 1.59mm. |
| 11 | Backing Plate: Black anodized Aluminum.
Thickness = 6.35mm. |

SG-BGA-6244 Drawing

© 2009 IRONWOOD ELECTRONICS, INC.
11351 Rupp Drive, Suite 400, Burnsville, MN 55337
Tele: (952) 229-8200
www.ironwoodelectronics.com

Status: Released

Scale: -

Rev: B

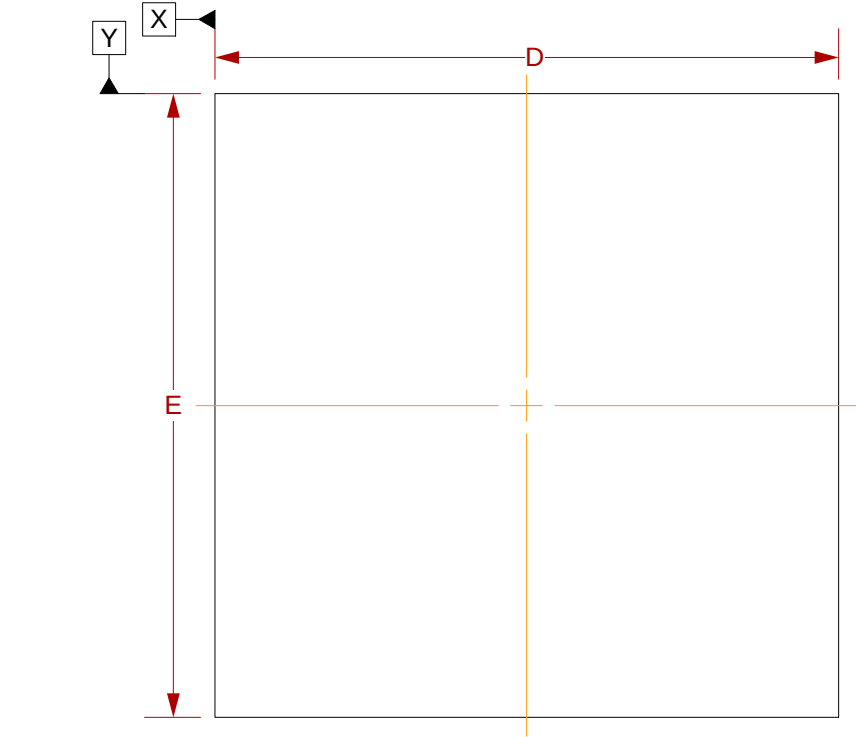
Drawing: J. Glab

Date: 12/05/07

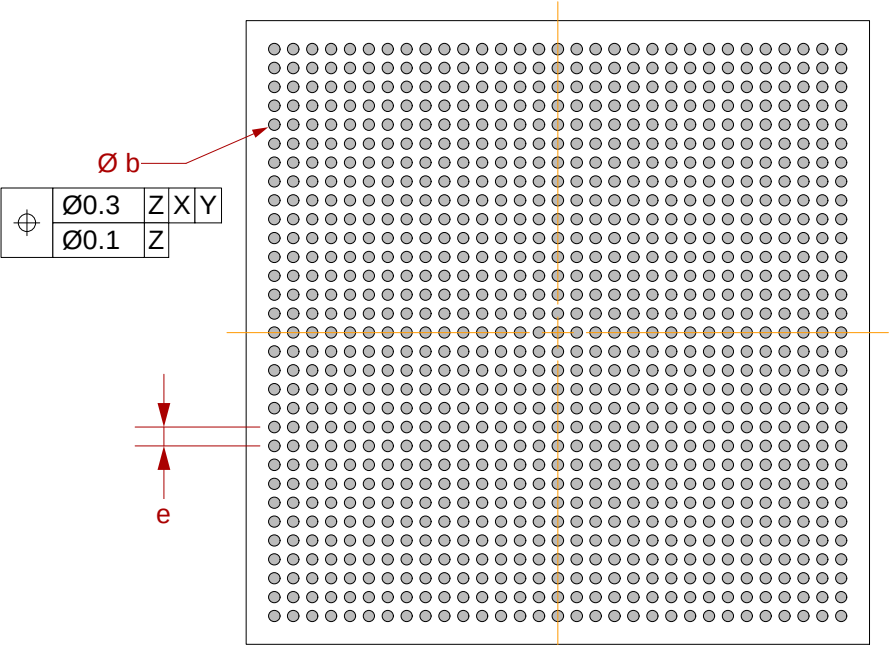
File: SG-BGA-6244 Dwg

Modified: 7/22/09, AE

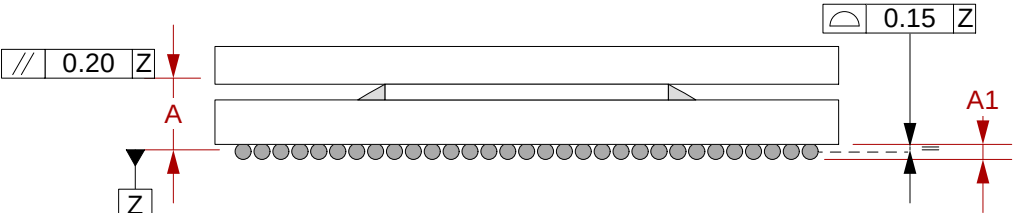
All tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.



Top View



Bottom View



Side View

1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		6.572
A1	0.71	0.91
b		0.85
D	32.5	
E	32.5	
e	1.0 BSC	

Array: 31x31

SG-BGA-6244 Drawing		Status: Released	Scale: -	Rev: B
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com		Drawing: J. Glab	
	File: SG-BGA-6244 Dwg		Date: 12/05/07 Modified: 7/22/09, AE	

